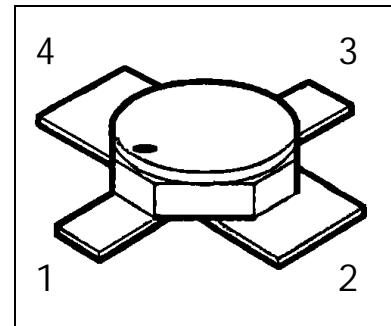


HiRel NPN Silicon RF Transistor

- **HiRel Discrete and Microwave Semiconductor**
- For low power amplifiers at collector currents from 0,2 mA to 2,5 mA.
- Hermetically sealed microwave package
- $f_T = 6,5$ GHz
 $F = 2.6$ dB at 2 GHz
-  **esa Space Qualified**
ESA/SCC Detail Spec. No.: 5611/006
Type Variant No. 01



ESD: Electrostatic discharge sensitive device,
observe handling precautions!

Type	Marking	Ordering Code	Pin Configuration				Package
BFY180 (ql)	-	see below	C	E	B	E	Micro-X1

(ql) Quality Level: P: Professional Quality, Ordering Code: Q97301013
H: High Rel Quality, Ordering Code: on request
S: Space Quality, Ordering Code: on request
ES: ESA Space Quality, Ordering Code: Q97111419

(see order instructions for ordering example)

Maximum Ratings

Parameter	Symbol	Values	Unit
Collector-emitter voltage	V_{CEO}	8	V
Collector-emitter voltage, $V_{BE}=0$	V_{CES}	15	V
Collector-base voltage	V_{CBO}	15	V
Emitter-base voltage	V_{EBO}	2	V
Collector current	I_C	4	mA
Base current	I_B	0.5 ¹⁾	mA
Total power dissipation, $T_S \leq 176^\circ\text{C}$ ^{2), 3)}	P_{tot}	30	mW
Junction temperature	T_j	200	°C
Operating temperature range	T_{op}	-65...+200	°C
Storage temperature range	T_{stg}	-65...+200	°C

Thermal Resistance

Junction-soldering point ³⁾	$R_{th JS}$	< 805	K/W	
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Notes.:

- 1) The maximum permissible base current for V_{FBE} measurements is 3mA (spot-measurement duration < 1s)
- 2) At $T_S = + 176^\circ\text{C}$. For $T_S > + 176^\circ\text{C}$ derating is required.
- 3) T_S is measured on the collector lead at the soldering point to the pcb.

Electrical Characteristics

at $T_A=25^\circ\text{C}$; unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Collector-base cutoff current $V_{CB} = 10\text{ V}, I_E = 0$	I_{CBO}	-	-	100	μA
Collector-emitter cutoff current $V_{CE} = 8\text{ V}, I_B = 0,05\mu\text{A}$ ^{1.)}	I_{CEX}	-	-	50	μA
Collector-base cutoff current $V_{CB} = 8\text{ V}, I_E = 0$	I_{CBO}	-	-	50	nA
Emitter base cutoff current $V_{EB} = 2\text{ V}, I_C = 0$	I_{EBO}	-	-	25	μA
Emitter base cutoff current $V_{EB} = 1\text{ V}, I_C = 0$	I_{EBO}	-	-	0.5	μA

Notes:

- 1.) This Test assures $V(BR)_{CEO} > 8\text{V}$

Electrical Characteristics (continued)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Base-Emitter forward voltage $I_E = 3 \text{ mA}, I_C = 0$	V_{FBE}	-	-	1	V
DC current gain $I_C = 0,25 \text{ mA}, V_{CE} = 1 \text{ V}$	h_{FE}	30	100	175	-
AC Characteristics					
Transition frequency $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 500 \text{ MHz}$	f_T	5,5	6.5	-	GHz
Collector-base capacitance $V_{CB} = 5 \text{ V}, V_{BE} = vbe = 0, f = 1 \text{ MHz}$	C_{CB}	-	0.15	0.24	pF
Collector-emitter capacitance $V_{CE} = 5 \text{ V}, V_{BE} = vbe = 0, f = 1 \text{ MHz}$	C_{CE}	-	0.34	-	pF
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, V_{CB} = vcb = 0, f = 1 \text{ MHz}$	C_{EB}	-	0.25	0.4	pF
Noise Figure $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz},$ $Z_S = Z_{Sopt}$	F	-	2.6	3.2	dB
Power gain $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz}$ $Z_S = Z_{Sopt}, Z_L = Z_{Lopt}$	G_{ma} ¹⁾	12	13.5	-	dB
Transducer gain $I_C = 2 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz}$ $Z_S = Z_L = 50 \Omega$	$ S_{21e} ^2$	6.5	8	-	dB

Notes.:

$$1) \quad G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$

Order Instructions:

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....
BFY180 (ql)
(ql): Quality Level

Ordering Example:

Ordering Code: Q97111419
BFY180 ES
For BFY180 in ESA Space Quality Level

Further Informations:

See our WWW-Pages:

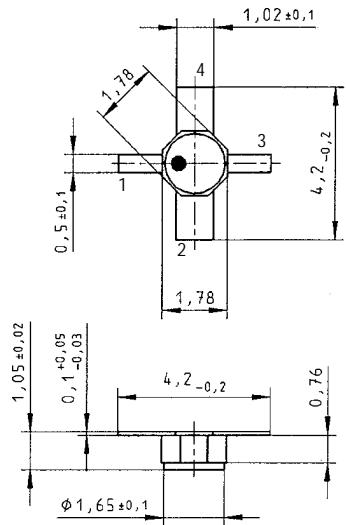
- Discrete and RF-Semiconductors (Small Signal Semiconductors)
www.infineon.com/products/discrete/hirel.htm

- *HiRel* Discrete and Microwave Semiconductors
www.infineon.com/products/discrete/hirel.htm

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Micro-X1 Package



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